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PCN# :P217A
Issue Date : Feb. 06, 2012

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product :May. 06, 2012

Expected First Date Code of Changed Product :1207

Last Date for Shipment of Unchanged Product :May. 06, 2012

Description of Change (From) :

FAN5353MPX & FAN5354MPX assembled in MLP 3.0 x 3.5mm package using lead frame with full metal connecting bar.

Description of Change (To) :

FAN5353MPX & FAN5354MPX assembled in MLP 3.0 x 3.5mm package using lead frame with half etched connecting bar.

Reason for Change:
The qualified lead frame design is to resolve excessive burring induce during package sawing. This change minimizes burr length and prevents shorting of terminals during customer reflow process. There is no change in lead frame material.

There are no changes to the currently approved assembly facilities or any other materials used to produce these products. Package outline drawings of the affected products remain un-changed. Affected products will be fully compliant to all published data sheet specifications.

Affected Product(s):

FAN5353MPX	FAN5354MPX	

A qualification data for MLP, 12L 3.5x3.0 New Design Leadframe to Resolve Saw Burr & Saw Smear Issue

Qualification Plan	Device	Package	Process	No. of Lots
Q20110070	FAN5353MPX	MLP 3.5x3.0 In 12-lead	FS50BPOA	3

Test Description:	Condition:	Standard :	Duration:	Results:
MSL1 Precondition	260C, 3 cycles	**JESD22-A113**		0/231
MSL1	260C, 3 cycles	**J-STD_020**		0/33
Temperature Cycle	-65C, 150C	**JESD22-A104**	500 cycles	0/231
Bond Pull	5.0g	**JESD22-C100**		0/15
Bond Shear	40.0g	**AEC-Q100-001**		0/15
Die Shear	0.4g/mil sq	**MIL-STD-883-2019**		0/15
Solderability CA	Condition C steam aging (8hrs), Condition A solder Dip (215 for 5 sec)	**JESD22-B102**		0/33
Solderability CB	Condition C steam aging (8hrs), Condition A solder Dip (245 for 5 sec)	**JESD22-B102**		0/33